



Material Content Data Sheet



Sales Product Name		BSZ110N06NS3 G		Issued		19. July 2018		
MA#		MA001044830						
Package		PG-TSDSON-8-2		Weight*		38.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.296	3.38	3.38	33767	33767
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		218	
	non noble metal	iron	7439-89-6	0.168	0.44		4368	
wire	non noble metal	copper	7440-50-8	6.808	17.74	18.21	177372	182013
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	931	931
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		905
	plastics	epoxy resin	-	1.788	4.66		46597	
	inorganic material	silicondioxide	60676-86-0	15.540	40.49	45.24	404897	452399
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10087	10087
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25080	25080
solder	noble metal	silver	7440-22-4	0.037	0.10		957	
	non noble metal	tin	7440-31-5	0.029	0.08		766	
	non noble metal	lead	7439-92-1	1.404	3.66	3.84	36571	38294
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		112	
	non noble metal	iron	7439-89-6	0.086	0.22		2247	
	non noble metal	copper	7440-50-8	3.501	9.12	9.35	91222	93609
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3932	
	non noble metal	copper	7440-50-8	6.127	15.96	16.37	159642	163820
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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